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Contents

vii Conference Committee

DTCO AND STCO I

12052 02 **Challenges with SOT-MRAM integration towards N5 node and beyond** [12052-1]

12052 03 **A yield prediction model and cost of ownership for productivity enhancement beyond imec 5nm technology node** [12052-2]

12052 04 **Zigzag nanosheets transistor introduction: a path for nanosheet FET architecture scalability** [12052-3]

12052 05 **Spectrum optimization during SMO: simultaneous source-mask-laser spectrum optimization** [12052-4]

DTCO AND STCO II

12052 08 **Design process integration enabling the productivity enhancement for nanoimprint lithography** [12052-7]

12052 0A **Machine learning based error classification for curvilinear designs** [12052-8]

12052 0B **A machine learning based framework for correcting the interlayer misalignment of physical design in 3D-NAND flash** [12052-9]

12052 0C **Design and mask optimization toward low dose EUV exposure** [12052-10]

COMPUTATIONAL PATTERNING

12052 0F **Design, patterning, and process integration overview for 2nm node** [12052-13]

12052 0G **Computational lithographic study of 0.55 NA EUV single patterning for metal layers for the 2nm logic node and beyond** [12052-14]

12052 0H **A novel contrast-aware SMO at 7nm technology node** [12052-16]

12052 0I **A novel approach of virtual etch target (VET) for efficient litho-to-etch pattern fidelity correction** [12052-17]

12052 0J **Computation of transmission cross coefficients for pixelated illumination source** [12052-18]

ADVANCED COMPUTATIONAL VERIFICATION

12052 0K **Machine learning architecture evaluation for fast and accurate weak point detection** [12052-29]

12052 0L **Robust qualification flows for DRC decks using high coverage synthetic layout generation** [12052-30]

12052 0M **Hotspot pattern synthesis using generative network with hotspot probability model** [12052-31]

12052 0N **Smart down-sampling using SONR** [12052-32]

12052 0O **Dynamic pattern match searching flow to enable precise hotspot detection** [12052-33]

12052 0Q **Pareto front optimization for enhanced model prediction accuracy** [12052-36]

AI, DEEP LEARNING AND MACHINE LEARNING

12052 0S **Refragmentation through machine learning classifier for fast and accurate optical proximity correction** [12052-20]

12052 0T **Data augmentation in EUV lithography simulation based on convolutional neural network** [12052-21]

12052 0X **Novel methodology for SRAF placement over a machine learning generated probability map** [12052-25]

12052 0Y **Matrix-OPC with fast MEEF prediction using artificial neural network** [12052-26]

12052 0Z **Machine learning OPC with generative adversarial networks** [12052-27]

DESIGN FOR MANUFACTURABILITY AND YIELD

12052 10 **Methodologies to handle large volumes of design and defect data for improved pre-silicon defect prediction** [12052-37]

12052 11 **Retargeting-aware design for manufacturability (DFM) checks using machine learning** [12052-38]

12052 12 **Wafer level analysis and simulation of back end of line chemical mechanical polishing processes** [12052-39]

12052 13 **A machine learning-based solution for modulated image analysis in lithography process stability diagnosis** [12052-41]

POSTER SESSION

12052 14 **Optimization of the EUV mask structures for mitigating the forbidden pitch in 5nm node** [12052-40]

12052 15 **Pattern based automation of ETest gauge checks for MDP** [12052-42]

12052 18 **Source optimization for forbidden pitch resolving in metal layer of 5nm technology node** [12052-45]

12052 1B **Etch proximity correction for dense array patterns** [12052-49]

12052 1C **Effective OPC model calibration using machine learning** [12052-50]

12052 1E **OPC optimization and hotspot detection using pattern diffing** [12052-52]